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Renesas Technology Corp. Customer Support Dept. April 1, 2003



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3-to-8-line Decoder/Demultiplexer



ADE-205-549 (Z) 1st. Edition Sep. 2000

Description

The HD74HCT238 has 3 binary select inputs (A, B, and C). If the device is enabled these inputs determined which one of the eight normally high outputs will go low. Two active low and one active high enables $(G_1, \overline{G_{2A}})$ and $\overline{G_{2B}})$ are provided to ease the cascading of decoders.

Features

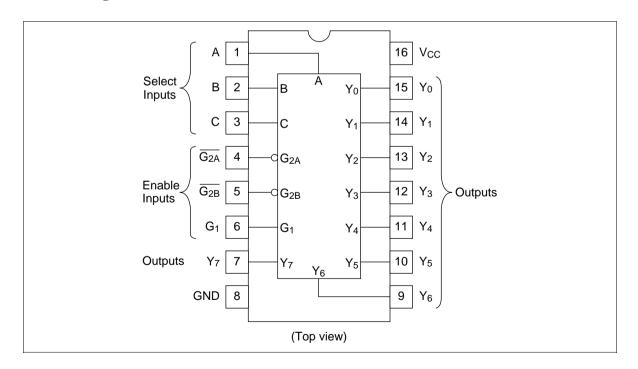
- LSTTL Output Logic Level Compatibility as well as CMOS Output Compatibility
- High Speed Operation: t_{pd} (A, B, C to Y) = 18.5 ns typ ($C_L = 50 \text{ pF}$)
- High Output Current: Fanout of 10 LSTTL Loads
- Wide Operating Voltage: $V_{CC} = 4.5$ to 5.5 V
- Low Input Current: 1 μA max
- Low Quiescent Supply Current: I_{CC} (static) = 4 μ A max (Ta = 25°C)

Function Table

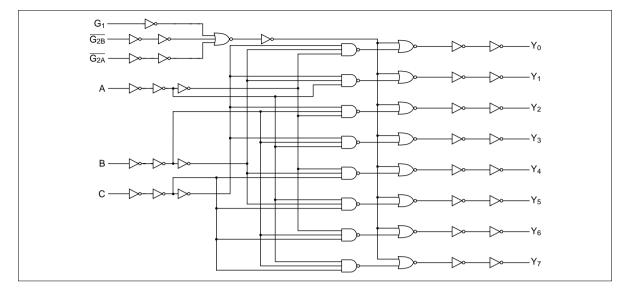
Inputs

Enable			Select			Outp	Outputs							
G ₁	G _{2A}	G _{2B}	С	В	Α	Y ₀	Y ₁	Y ₂	Y ₃	Y ₄	Y ₅	Y_6	Y ₇	
X	Χ	Н	Χ	Χ	Χ	L	L	L	L	L	L	L	L	
X	Н	Χ	Χ	Χ	Χ	L	L	L	L	L	L	L	L	
L	Χ	Χ	Χ	Χ	Χ	L	L	L	L	L	L	L	L	
Н	L	L	L	L	L	Н	L	L	L	L	L	L	L	
Н	L	L	L	L	Н	L	Н	L	L	L	L	L	L	
Н	L	L	L	Н	L	L	L	Н	L	L	L	L	L	
Н	L	L	L	Н	Н	L	L	L	Н	L	L	L	L	
Н	L	L	Н	L	L	L	L	L	L	Н	L	L	L	
Н	L	L	Н	L	Н	L	L	L	L	L	Н	L	L	
Н	L	L	Н	Н	L	L	L	L	L	L	L	Н	L	
Н	L	L	Н	Н	Н	L	L	L	L	L	L	L	Н	

Pin Arrangement



Logic Diagram



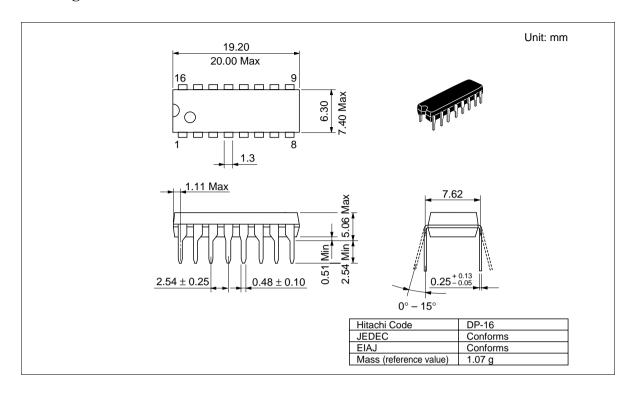
DC Characteristics

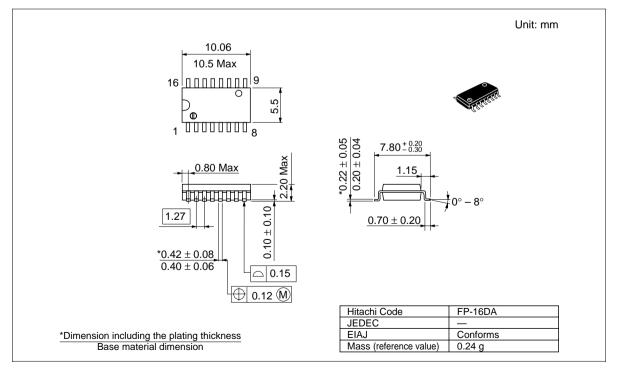
		Ta = 25°C			Ta = -40 to +85°C		_	Test Conditions	
Item	Symbol	Min	Тур	Max	Min	Max	Unit	V _{cc} (V)	
Input voltage	V_{IH}	2.0	_	_	2.0	_	V	4.5 to 5.5	
	V _{IL}	_	_	8.0	_	8.0	V	4.5 to 5.5	
Output voltage	V_{OH}	4.4	_	_	4.4	_	V	4.5	Vin = V_{IH} or V_{IL} I_{OH} = $-20 \mu A$
		4.18	3 —	_	4.13	_		4.5	$I_{OH} = -4 \text{ mA}$
	V_{OL}	_	_	0.1	_	0.1	V	4.5	Vin = V_{IH} or V_{IL} I_{OL} = 20 μ A
		_	_	0.26	_	0.33		4.5	$I_{OL} = 4 \text{ mA}$
Input current	lin	_	_	±0.1	_	±1.0	μΑ	5.5	$Vin = V_{CC}$ or GND
Quiescent supply current	I _{cc}	_	_	4.0	_	40	μΑ	5.5	Vin = V_{CC} or GND, lout = 0 μ A

AC Characteristics ($C_L = 50 \text{ pF}$, Input $t_r = t_f = 6 \text{ ns}$)

		Ta = 25°C			Ta = -40 to +85°C			Test Co	onditions
Item	Symbol	Min	Тур	Max	Min	Max	Unit	V _{cc} (V)	<u>-</u>
Propagation delay	t _{PLH}	_	18	30	_	38	ns	4.5	A, B or C to Y
time	t _{PHL}	_	19	30	_	38	_	4.5	_
	t _{PLH}	_	17	30	_	38	ns	4.5	G _{2A} to Y
	t _{PHL}	_	17	30	_	39	=	4.5	_
	t _{PLH}	_	17	30	_	38	ns	4.5	G _{2B} to Y
	t _{PHL}	_	17	30	_	38	=	4.5	_
	t _{PLH}	_	17	30	_	38	ns	4.5	G₁ to Y
	t _{PHL}	_	17	30	_	38	_	4.5	_
Output rise/fall	t _{TLH}	_	5	15	_	19	ns	4.5	
time	t_{THL}								
Input capacitance	Cin	_	5	10	_	10	pF	_	· · · · · · · · · · · · · · · · · · ·

Package Dimensions





Unit: mm 9.9 10.3 Max 16 _______9 3.95 1 1000000 8 1.27 *0.22 ± 0.03 0.20 ± 0.03 1.75 Max 6.10 + 0.10 1.08 0.635 Max 0° – 8° $0.60^{+0.67}_{-0.20}$ $^{*}0.42 \pm 0.08 \over 0.40 \pm 0.06$ 0.15 0.25 (M) Hitachi Code FP-16DN JEDEC Conforms *Dimension including the plating thickness EIAJ Conforms Base material dimension Mass (reference value) 0.15 g

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Semiconductor & Integrated Circuits. Nippon Bldg., 2-6-2, Ohte-machi, Chiyoda-ku, Tokyo 100-0004, Japan Tel: Tokyo (03) 3270-2111 Fax: (03) 3270-5109

URL NorthAmerica http://semiconductor.hitachi.com/ http://www.hitachi-eu.com/hel/ecg Europe Asia http://sicapac.hitachi-asia.com Japan http://www.hitachi.co.jp/Sicd/indx.htm

For further information write to:

Hitachi Semiconductor (America) Inc. 179 East Tasman Drive, San Jose,CA 95134 Tel: <1> (408) 433-1990 Germany

Hitachi Europe GmbH Electronic Components Group Dornacher Straße 3 D-85622 Feldkirchen, Munich Fax: <1>(408) 433-0223 Tel: <49> (89) 9 9180-0 Fax: <49> (89) 9 29 30 00

Hitachi Europe Ltd. Electronic Components Group. Whitebrook Park Lower Cookham Road Maidenhead

Berkshire SL6 8YA, United Kingdom Tel: <886>-(2)-2718-3666 Tel: <44> (1628) 585000 Fax: <44> (1628) 585160

Hitachi Asia Ltd. Hitachi Tower 16 Collyer Quay #20-00, Singapore 049318 Tel: <65>-538-6533/538-8577 Fax: <65>-538-6933/538-3877 URL: http://www.hitachi.com.sg

Hitachi Asia Ltd. (Taipei Branch Office) 4/F, No. 167, Tun Hwa North Road, Hung-Kuo Building, Taipei (105), Taiwan

Fax: <886>-(2)-2718-8180 Telex: 23222 HAS-TP URL: http://www.hitachi.com.tw Hitachi Asia (Hong Kong) Ltd. Group III (Electronic Components) 7/F., North Tower, World Finance Centre, Harbour City, Canton Road Tsim Sha Tsui, Kowloon, Hong Kong

Tel: <852>-(2)-735-9218 Fax: <852>-(2)-730-0281 URL: http://www.hitachi.com.hk

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